## Supporting Information

# Low-Voltage and High Performance Multilayer MoS $\mathbf{M i}_{2}$ Field-effect Transistors with Graphene Electrodes 

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Figure S1. Atomic force microscopic image of a) $\mathrm{ML}_{\mathrm{MoS}}^{2}$ and b) corresponding height profile for ML $\mathrm{MoS}_{2}$ films. The thickness is about 7.2 nm , indicating $10 \mathrm{MoS}_{2}$ layers.


Figure S2. Atomic force microscopic image of a) CVD-grown SLG and b) corresponding height profile. The thickness is about 0.38 nm , indicating SLG. c) Resistivity as a function of back gate voltage ( $V_{\mathrm{bg}}$ ) for CVD grown SLG


Figure S3. a) Optical image of the fabricated device (device S\#2), CVD-grown SLG as the source-drain electrode, and $\mathrm{ML} \mathrm{MoS}_{2}$ as the channel material. b) Optical image of the fabricated top-gated ML $\mathrm{MoS}_{2}$ transistor. The $\mathrm{ML} \mathrm{MoS}_{2}$ is covered with 15 -nm-thick film of ALDdeposited $\mathrm{Al}_{2} \mathrm{O}_{3}$ acting as a gate dielectric and $\mathrm{Cr} / \mathrm{Au}$ with $5 / 80 \mathrm{~nm}$ for the top-gated electrodes. c) Plot of $I_{D S}-V_{b g}$ of the ML $\mathrm{MoS}_{2}$ transistor after $\mathrm{Al}_{2} \mathrm{O}_{3}$ deposition at $V_{D S}=0.02 \mathrm{~V}$. Mobility of device $\mathrm{S} \# 2$ is estimated found to be $466 \mathrm{~cm}^{2} / \mathrm{Vs}$.

